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Technical Publications (Partial listing of over 30 papers)

A. Burkhart, **"Chip Packaging Materials: No Longer an Afterthought?,"** Global Semiconductor, October 2003

H. Zhou, Z. Tang, Frank G. Shi, N. Zhang (University of California-Irvine) , Art Burkhart, Maurice Edwards, "**Assembling of Fiber Collimators for Photonic Devices**," in Proc. 52nd ECTC IEEE., San Diego, CA, USA, 27-31 May 2002, pp. 821-827.

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Dr. Ben Santos, Art Burkhart, %**Advanced Wafer Level CSP Packaging Using New Liquid Bismaleimide Polymers**,+SMTA Pan Pacific Symposium 2001

J. Huneke, R. Weaver, R. Jaeger, B. Santos, K. Yang, C. Naito, M. Todd, A. Burkhart, G. Carson, "**Die Attach and Encapsulants for High-Temperature Reflow**," HDI magazine, May 2001. A*dapted from presentation at APEX conference January, 2001.*

J. Schreier, A. Burkhart **"High Performance Coplanar Finishes for BGA and High Density Substrates,"** November 2000

A. Burkhart **"Recent Developments: Taking a Closer Look at Solderable Surface Finishes,"** PC Fab, December 1998
A Burkhart, K. Johal, **"Electroless Palladium Surface Finish for BGAs, CSPs, and Flip Chip Applications,"** Surface Mount International Conference, Aug. 1998
A. Burkhart **"High Density PCBs,"** PC Fab, July 1998
A. Burkhart, M. Grosse, M. Nguyen "**Novel Snap Cure Die Attach for In-Line Processing**," Solid State Technology, June 1995

Nguyen, M., N. Chien, I.Y. Grosse, M.B. Chau, M.M. Burkhart, D.A. %**Polycyanate Die Attach Adhesives for Microelectronic Applications**," 45th Electronic Components and Technology Conference, 1995. Proceedings, May 1995

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A. Burkhart, "**New Epoxies for Advanced Surface Mount Applications,"** Surface Mount International Conference, Aug. 1991

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A. Burkhart, M. Bonneau **"Snap Cure Epoxy Die Attach for Automated Inline Assembly,"** MEPPE Focus Conference, 1991

J. Emerson (AT&T Bell Laboratories), A. Burkhart, et al **"Robust Encapsulation of Hybrid Devices,"** Proceedings of the 40th Electronic Components and Technology Conference, May 1990

T. Ohnishi, K. Hashimoto and S. Wakamoto (Sharp, Japan), Y. Sagami (Hysol Ltd. Japan), A. Burkhart, "**UV Light Transparent Epoxy Encapsulation for Erasable SMT Memory Cards**," Surface Mount Technology, December 1989 (Cover Story)

A. Burkhart, **"New Epoxies for Hybrid Circuit Applications,"** Hybrid Circuit Technology, October 1988

A. Burkhart, **"Third Generation Epoxies: Semiconductor Resins Cross the Line"** Circuits Manufacturing, February 1988

Art Burkhart, Mark Bonneau; **"Considerations for Choosing Chip-On-Board Encapsulants"**, Electronics, Sep., 1985